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ECL Products	

10231
Flip-Flop

Dual D-Type Master-Slave Flip-Flop (High-Speed)

FEATURES

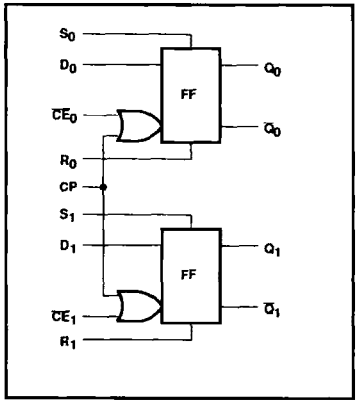
- **Typical propagation delay: 2.0ns**
- **Typical supply current ($-I_{EE}$): 52mA**

DESCRIPTION

The 10231 is a High-Speed Dual D-type Master-Slave Flip-Flop. It contains Asynchronous Set (S) and Reset (R) which override Clock (CP) and Clock Enable ($\overline{CE}_n$) inputs. Each flip-flop may be clocked separately by using the enable inputs for the clocking function and holding the Clock in the Low-State. For the two flip-flops to be clocked, the Clock must be used with the clock Enable inputs held in the Low-State.

The outputs of the 10231 change state with the positive transition of the Clock. Due to the master-slave structure of the device, a change in the information present at the data (D) input will not modify the output information at any other time. All unused inputs must be tied to V_{IL} or V_{EE}.

LOGIC DIAGRAM



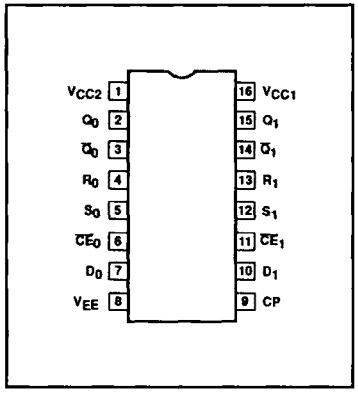
ORDERING INFORMATION

DESCRIPTION	ORDER CODE
16-Pin Plastic DIP	10231N
16-Pin Ceramic DIP	10231F

PIN DESCRIPTION

PINS	DESCRIPTION
D_0, D_1	Data Inputs
CP	Clock Input
$\overline{CE}_0$, $\overline{CE}_1$	Clock Enable Inputs
S_0, S_1	Set Inputs
R_0, R_1	Reset Inputs
Q_0, Q_1, $\overline{Q}_0$, $\overline{Q}_1$	Data Outputs

PIN CONFIGURATION



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FUNCTION TABLES

SYNCHRONOUS OPERATION

INPUTS			OUTPUT
D_n	C_P	$\overline{C_E}$*	Q_{n+1}**
L	L	L	Q_n
L	L	H	Q_n
L	H	L	L
L	H	H	Q_n
H	L	L	Q_n
H	L	H	Q_n
H	H	L	H
H	H	H	Q_n

* Conditions for CP and $\overline{CE}$ may be interchanged. In this table $\overline{CE}$ is static, while for CP and H represent a transition from Low to High between t_n and T_{n+1}.

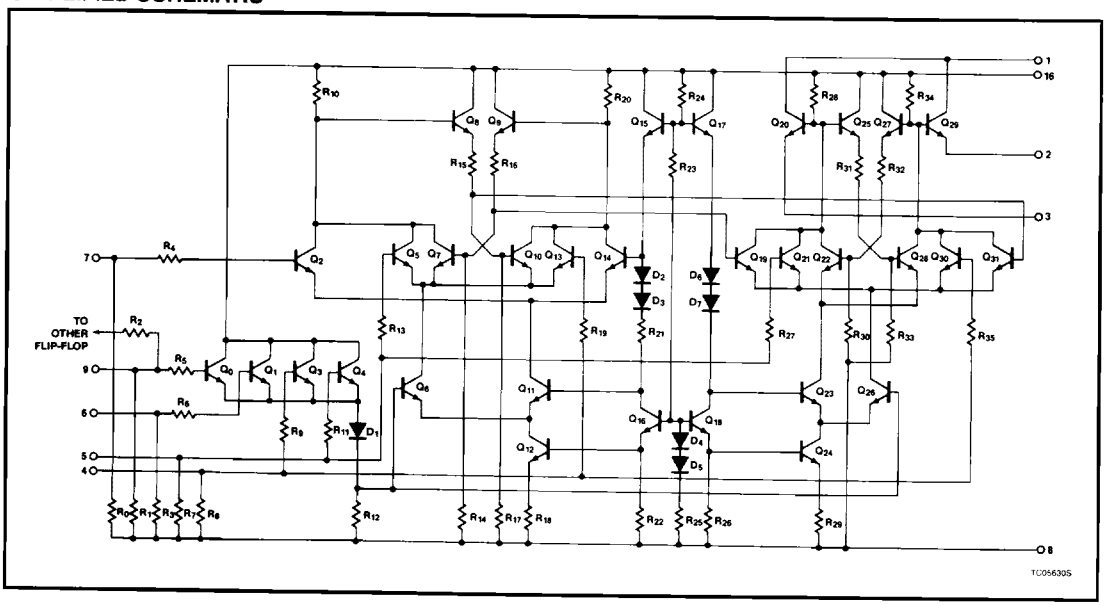
** R and S = Low

ASYNCHRONOUS OPERATION

INPUTS		OUTPUT
R	S	Q_{n+1}
L	L	Q_n
L	H	H
H	L	L
H	H	N

H = High Voltage Level
L = Low Voltage Level
N = Not allowed

SIMPLIFIED SCHEMATIC



ABSOLUTE MAXIMUM RATINGS

SYMBOL	PARAMETER		LIMITS	UNIT
V_{EE}	Supply voltage		–8.0	V
V_{IN}	Input voltage (V_{IN} should never be more negative than V_{EE})		0 to V_{EE}	V
I_O	Output source current (continuous)		–50	mA
T_S	Storage temperature range		–55 to +150	°C
T_J	Maximum junction temperature	Ceramic Package	+165	°C
		Plastic Package	+150	°C

NOTE:
Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted, these limits are specified over the operating ambient temperature range.

DC OPERATING CONDITIONS

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			MIN.	NOM.	MAX.	
V_{CC1}, V_{CC2}	Circuit ground		0	0	0	V
V_{EE}	Supply voltage (negative)			–5.2		V
V_{IH}	High level input voltage	T_A = –30°C			–890	mV
		T_A = +25°C			–810	mV
		T_A = +85°C			–700	mV
V_{IHT}	High level input threshold voltage	T_A = –30°C	–1205			mV
		T_A = +25°C	–1105			mV
		T_A = +85°C	–1035			mV
V_{ILT}	Low level input threshold voltage	T_A = –30°C			–1500	mV
		T_A = +25°C			–1475	mV
		T_A = +85°C			–1440	mV
V_{IL}	Low level input voltage	T_A = –30°C	–1890			mV
		T_A = +25°C	–1850			mV
		T_A = +85°C	–1825			mV
T_A	Operating ambient temperature range		–30	+25	+85	°C

NOTE:
When operating at other than the specified V_{EE} voltage (–5.2V), the DC and AC Electrical Characteristics will vary slightly from specified values.

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DC ELECTRICAL CHARACTERISTICS

$V_{CC1} = V_{CC2}$ = ground, $V_{EE} = -5.2V \pm 0.010V$, $T_A = -30°C$ to $+85°C$ output loading 50Ω to $-2.0V \pm 0.010V$ unless otherwise specified[1,3]

SYMBOL	PARAMETER		TEST CONDITIONS[2]		LIMITS MIN.	LIMITS TYP.	LIMITS MAX.	UNIT
V_{OH}	High level output voltage		$T_A = -30°C$	For Q outputs, apply V_{IHMAX} to S_n inputs with V_{ILMIN} applied to all other inputs. For $\overline{Q}$ outputs, apply V_{IHMAX} to R_n inputs with V_{ILMIN} applied to all other inputs.	−1060		−890	mV
			$T_A = +25°C$		−960		−810	mV
			$T_A = +85°C$		−890		−700	mV
V_{OHT}	High level output threshold voltage		$T_A = -30°C$	For Q outputs, apply V_{IHT} to S_n inputs, with V_{ILMIN} applied to all other inputs. For $\overline{Q}$ outputs, apply V_{IHT} to R_n inputs, with V_{ILMIN} applied to all other inputs.	−1080			mV
			$T_A = +25°C$		−980			mV
			$T_A = +85°C$		−910			mV
V_{OLT}	Low level output threshold voltage		$T_A = -30°C$	For Q outputs, apply V_{IHT} to R_n inputs, with V_{ILMIN} applied to all other inputs. For $\overline{Q}$ outputs, apply V_{IHT} to S_n inputs, with V_{ILMIN} applied to all other inputs.			−1655	mV
			$T_A = +25°C$				−1630	mV
			$T_A = +85°C$				−1595	mV
V_{OL}	Low level output voltage		$T_A = -30°C$	For Q outputs, apply V_{IHMAX} to R_n inputs, with V_{ILMIN} applied to all other inputs. For $\overline{Q}$ outputs, apply V_{IHMAX} to S_n inputs, with V_{ILMIN} applied to all other inputs.	−1890		−1675	mV
			$T_A = +25°C$		−1850		−1650	mV
			$T_A = +85°C$		−1825		−1615	mV
I_{IH}	High level input current	D_n, $\overline{CE}_n$ inputs	$T_A = -30°C$	Apply V_{IHMAX} to each input under test, one at a time, with V_{ILMIN} applied to all other inputs.			350	µA
			$T_A = +25°C$				220	µA
			$T_A = +85°C$				220	µA
		R_n, S_n inputs	$T_A = -30°C$				650	µA
			$T_A = +25°C$				410	µA
			$T_A = +85°C$				410	µA
		CP input	$T_A = -30°C$	Apply V_{IHMAX} to CP input with V_{ILMIN} applied to all other inputs.			460	µA
			$T_A = +25°C$				290	µA
			$T_A = +85°C$				290	µA
I_{IL}	Low level input current		$T_A = -30°C$	Apply V_{ILMIN} to each input under test, one at a time, with V_{IHMAX} applied to all other inputs.	0.5			µA
			$T_A = +25°C$		0.5			µA
			$T_A = +85°C$		0.3			µA
$-I_{EE}$	V_{EE} supply current		$T_A = -30°C$				72	mA
			$T_A = +25°C$			52	65	mA
			$T_A = +85°C$				72	mA
$\frac{\Delta V_{OH}}{\Delta V_{EE}}$	High level output voltage compensation		$T_A = +25°C$			0.016		V/V
$\frac{\Delta V_{OL}}{\Delta V_{EE}}$	Low level output voltage compensation					0.250		V/V
$\frac{\Delta V_{BB}}{\Delta V_{EE}}$	Reference bias voltage compensation					0.148		V/V

NOTES:

1. The specified limits represent the worst case values for the parameter. Since these worst case values normally occur at the supply voltage and temperature extremes, additional noise immunity can be achieved by decreasing the allowable operating condition ranges.
2. Conditions for testing shown in the tables are not necessarily worst case. For worst case testing guidelines, refer to DC Testing, Chapter 1, Section 3.
3. The specified limits shown in the DC Electrical Characteristics table can be met only after thermal equilibrium has been established. Thermal equilibrium is established by applying power for at least 2 minutes, while maintaining transverse airflow of 2.5 meters/sec (500 linear feet/min) over the device, mounted either in a test socket or on a printed circuit board. Test voltage values are given in the DC Operating Conditions table.

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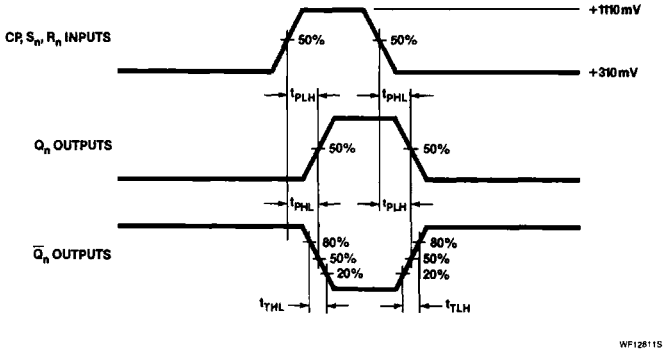
AC ELECTRICAL CHARACTERISTICS $V_{CC1} = V_{CC2} = \text{ground}, V_{EE} = -5.2V \pm 0.010V$

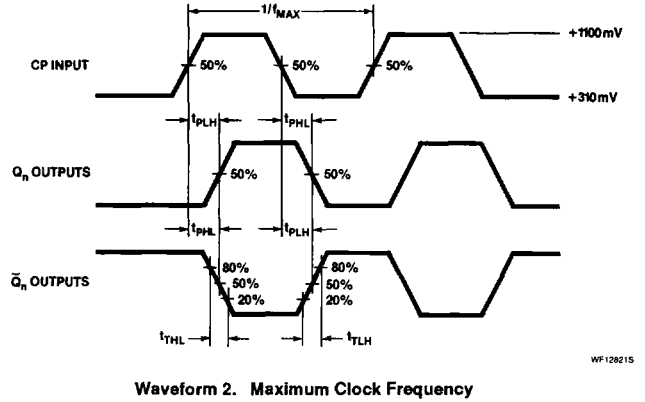
SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS							UNIT
			$T_A = -30°C$		$T_A = +25°C$			$T_A = +85°C$		
			MIN.	MAX.	MIN.	TYP.	MAX.	MIN.	MAX.	
f_{MAX}	Maximum clock frequency	Waveform 2	200		200	225		200		MHz
t_{PLH} t_{PHL}	Propagation delay CP to Q_n, $\overline{Q}_n$	Waveform 1	1.50 1.50	3.40 3.40	1.50 1.50	2.00 2.00	3.30 3.30	1.60 1.60	3.70 3.70	ns ns
t_{PLH} t_{PHL}	Propagation delay S_n, R_n to Q_n, $\overline{Q}_n$		1.10 1.10	3.40 3.40	1.10 1.10	2.00 2.00	3.30 3.30	1.20 1.20	3.70 3.70	ns ns
t_s	Setup time D_n to CP	Waveform 3	1.50		1.00			1.50		ns
t_h	Hold time CP to D_n	Waveform 3	0.90		0.75			0.90		ns
t_{TLH} t_{THL}	Transition time 20% to 80%, 80% to 20%	Waveform 1	0.90 0.90	3.30 3.30	1.00 1.00	1.30 1.30	3.10 3.10	1.00 1.00	3.60 3.60	ns ns

NOTE:
For AC test setup information, see AC Testing, Chapter 2, Section 3.

AC WAVEFORMS

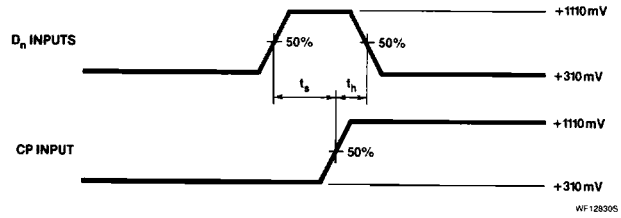


Waveform 1. Propagation Delay and Transition Times, CP, S_n, R_n Inputs to Outputs



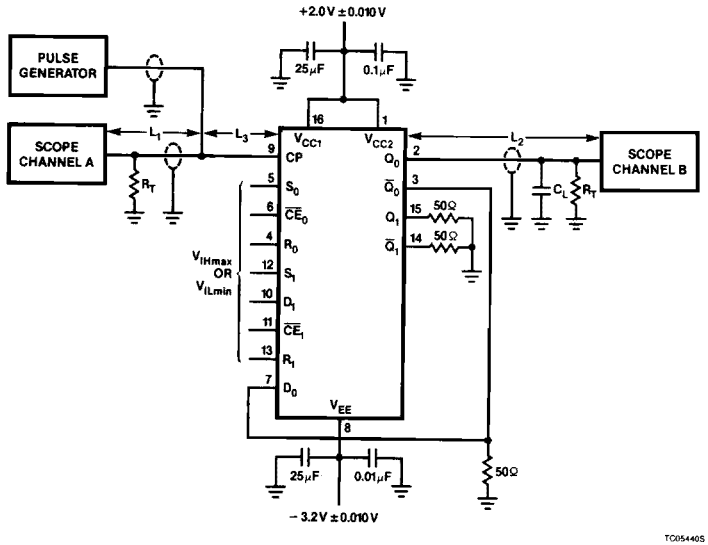
Waveform 2. Maximum Clock Frequency

AC WAVEFORMS (Continued)



Waveform 3. Setup and Hold Times for Data to Clock

TOGGLE FREQUENCY TEST CIRCUIT



NOTES:

1. $V_{CC1} = V_{CC2} = +2V \pm 0.010V$, $V_{EE} = -3.2V \pm 0.010V$.
2. Decoupling 0.1μF and 25μF from GND to V_{CC}. 0.01μF and 25μF from GND to V_{EE}. (0.01 and 0.1μF capacitors should be NPO Ceramic or MLC type). Decoupling capacitors should be placed as close as physically possible to the DUT and lead length should be kept to less than 1/4 inch (6mm).
3. All unused inputs should be connected to either HIGH or LOW state consistent with the LOGIC function required.
4. All unused outputs are loaded with 50Ω to GND.
5. L_1 and L_2 are equal length 50Ω impedance lines. L_3, the distance from the DUT pin to the junction of the cable from the Pulse Generator and the cable to the Scope, should not exceed 1/4 inch (6mm).
6. R_T = 50Ω terminator internal to Scope.
7. The unmatched wire stub between coaxial cable and pins under test must be less than 1/4 inch (6mm) long for proper test.
8. C_L = Fixture and stray capacitance ≤ 3pF.
9. Any unterminated stubs connected anywhere along the transmission line between the Pulse Generator and the DUT or between the DUT and the Scope should not exceed 1/4 inch (6mm) in length (refer to section on AC setup procedure).
10. All 50Ω resistors should have tolerance of ±1% or better.